TECHNICAL DATA SHEET

CATEGORY: **ALLOY**

NAME: **50Sn/50Pb**

FEATURES

- HIGH PURITY
- MELTING TEMPERATURE - 183°C-212°C

DESCRIPTION

50Sn/50Pb is composed of 50% Tin and 50% Lead. This is a high purity alloy suitable for electronic and industrial soldering applications. 50Sn/50Pb has a melting point of 183°C – 212°C. This alloy is available in solid and cored wire, foil, preforms, powder, solder paste, bar, ingot, and anode.

IMPURITY LEVELS IN PERCENT

Ag: 0.10	Au: 0.05	Cu: 0.08	Ni: 0.01
Al: 0.005	Bi: 0.25	Fe: 0.02	Sb: 0.05
As: 0.03	Cd: 0.005	In: 0.10	Zn: 0.005

MAJOR ALLOY INGREDIENTS IN PERCENT

Sn	Pb
50% ± 1.0%	Balance

TENSILE STRENGTH

Ultimate Tensile Strength (MPa)	Ultimate Tensile Strength (psi)
67.5	9790

HANDLING

- If this alloy is used in water soluble cored wire, the product will have a shelf life of 3 years. All other cored wire, solid wire, and bar solder products have an indefinite shelf life.
- This product contains lead, which is known to be a toxic element. Consult the Material Safety Data Sheet for specific handling procedures.

FLUX COMPATIBILITY

- 50Sn/50Pb is compatible with most electronic and industrial grade fluxes.

CLEANING

- Refer to data sheets provided by the flux manufacturer.

SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

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